



# 100% Material Declaration Data Sheet FG860

PK157 (v1.2) September 25, 2006

Material Declaration Data Sheet

**Average Weight: 10.904 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.1201</b>	<b>1.10%</b>
	Silicon	7440-21-3	100.00		0.1201	
<b>Die Attach Material</b>					<b>0.012</b>	<b>0.11%</b>
	Silver	7440-22-4	75.00		0.009	
	Resin	Trade Secret	25.00		0.003	
<b>Mold Compound</b>					<b>0.4135</b>	<b>7.31%</b>
	Epoxy Resins	Trade Secret	26.00		0.207	
	SiO2	60676-86-0	74.00	Filler	0.590	
<b>Laminate</b>					<b>0.7897</b>	<b>7.24%</b>
	Laminate	Trade Secret			0.481	
	Solder Mask	Trade Secret			0.168	
	Copper	7440-50-8		Metal Layer	0.122	
	Nickel	7440-02-0		Metal Layer	0.014	
	Gold	7440-57-5		Metal Layer	0.005	
<b>Heat Sink</b>					<b>7.0645</b>	<b>64.79%</b>
	Copper	7440-50-8	97.50		6.888	
	Iron	7439-89-6	2.35		0.166	
	Phosphorus	7723-14-0	0.003		0.0002	
	Zinc	7440-66-6	0.12		0.008	
<b>Heat Snk Plating</b>					<b>0.3292</b>	<b>3.02%</b>
	Nickel	7440-05-0	100.00		0.3292	
<b>Dam</b>					<b>0.0148</b>	<b>0.13%</b>
	Epoxy Resin	Trade Secret	100.00		0.0148	
<b>Bond Wire</b>					<b>0.0236</b>	<b>0.22%</b>
	Gold	7440-57-5	100.00		0.0236	
<b>Solder Balls</b>					<b>1.752</b>	<b>16.07%</b>
	Tin	7440-31-5	63.00		1.104	
	Lead	7439-92-1	37.00		0.648	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/27/06	1.0	Initial release.
6/15/06	1.1	100% Material Declaration.
9/25/06	1.2	Update component descriptions.